Unit: mm

0.41

DSC7505

Silicon NPN epitaxial planar type

For low frequency amplification

Features

- \bullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

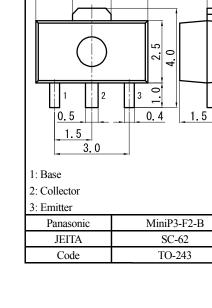
■ Marking Symbol: 5G

Packaging

DSC7505×0L Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	40	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	7	V
Collector current	I _C 3		A
Peak collector current	I_{CP}	5	A
Collector power dissipation *1	P _C	1	W
Junction temperature	T _j	150	°C
Operating ambient temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-55 to +150	°C



4.5

1.6

Note) *1: Printed circuit board: Copper foil area of 1 cm 2 or more, and the board thickness of 1.7 mm for the collector portion Absolute maximum rating without heat sink for P_C is $\;0.5\;W$

■ Electrical Characteristics $T_a = 25$ °C±3°C

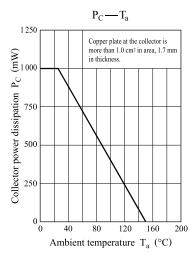
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$	230		600	
	h _{FE2}	$V_{CE} = 2 \text{ V}, I_{C} = 2 \text{ A}$	150			_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 3 \text{ A}, I_B = 0.1 \text{ A}$			1.0	V
Transition frequency *1	f_T	$V_{CE} = 6 \text{ V}, I_{C} = 50 \text{ mA}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			50	pF

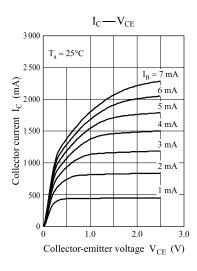
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

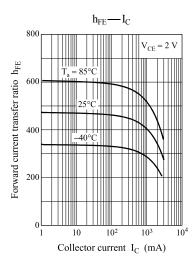
- 2. *1: Pulse measurement
 - *2: Rank classification

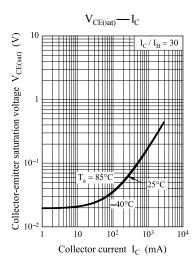
Code	Q	R	0	
Rank	Q	R	No-rank	
h _{FE1}	230 to 380	340 to 600	230 to 600	
Marking Symbol	5GQ	5GR	5G	

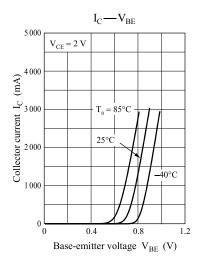
Product of no-rank is not classified and have no marking symbol for rank.

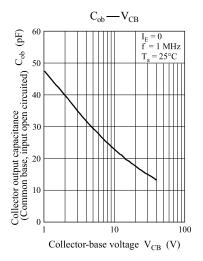


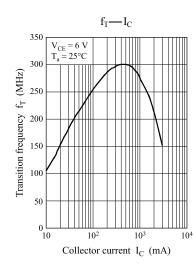








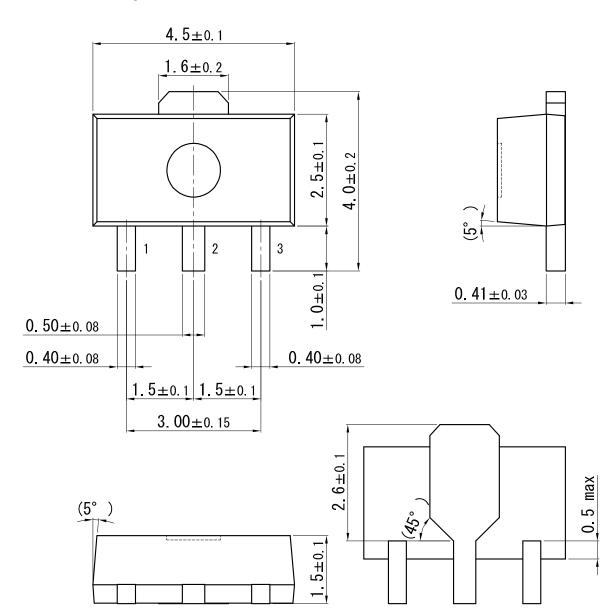




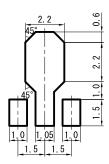
Ver. DED 2

MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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